

Abstract

In accordance with the invention, a temperature compensating device comprises one or more integrated sheet thermistors. Because the sheet thermistors are relatively thick and integral with the substrate, they are less susceptible to changes in air temperature and to temperature gradients. Moreover, the sheet thermistors can be made smaller in area, permitting more compact, less expensive devices that exhibit improved high frequency performance. The devices can advantageously be fabricated using the low temperature co-fired ceramic (LTCC) process.

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